Claims:

1. A wafer-level method for applying $N \geq 2$ first elements to a first side of a substrate, the substrate providing at the first side a first surface, the method comprising

a) replicating at least N barrier members and an initial first element on the first surface of the substrate by an embossing-type or molding-type process, wherein the initial element and at least one of the at least N barrier members are simultaneously and integrally formed, and wherein each of the N barrier members is associated with one of the N first elements;

b) bringing a respective first amount of a hardenable material in a flowable state in contact with the first surface, the respective first amount of hardenable material being subsequently used to form a respective one of the N first elements;

c) performing an embossing-type replication technique that includes pressing a replication tool into the first amount of the hardenable material;

d) controlling a flow of the respective associated first amount of hardenable material on the first surface, during the embossing-type replication technique, by means of a respective barrier member integrally formed with the initial first element;

e) hardening the respective associated first amount of hardenable material to form the respective one of the N first elements.

2. The method according to claim 1, wherein a contact angle for the hardenable material on the barrier member amounts to at most 90°.

3. The method according to claim 1, wherein the hardenable material is hardenable via the introduction of energy.

4. The method according to claim 1, wherein each of the N first elements is or comprises one or more of

— a replicated structure replicated at the first surface comprising steps b), c) and d);

— an item to be bonded to the first surface;

— a micro-optical component;

— a passive optical component;

— an active optical component;

— an electronic component;

— a light emitting element;

— a light-detecting element;

— a micro-mechanical component;

— a micro-fluidic component;

— a portion of a wafer.

5. The method according to claim 1, wherein each of the N barrier members comprises a protrusion protruding beyond an average level described by the first surface, the respective protrusion comprising a first partial surface, said first partial surface is at least oen of:

- facing towards the respective first element in its position at the end of step d) and being horizontally aligned within ±35°, and a second partial surface facing away from the respective first element in its position at the end of step d),

wherein the first partial surface is, at the end of step d), at least partially covered by hardenable material of the respective associated first amount of hardenable material, and

wherein the second partial surface is, at the end of step d), free from hardenable material of the respective associated first amount of hardenable material.

6. The method according to claim 1, wherein each of the N barrier members forms a protrusion protruding beyond an average level described by the first surface by at least 2 µm or by at most 150 µm or by both, at least 2 µm and at most 150 µm

7. The method according to claim 1, wherein a contact angle for the hardenable material on the barrier member amounts to at most 45°.

8. The method according to claim 1, wherein the hardenable material is hardenable by one or both of heating it and irradiating it with electromagnetic radiation.

9. The method according to claim 1, wherein each of the N first elements is an optical element.

10. The method according to claim 5, wherein the first and second partial surface are adjoining at an edge and the first partial surface is, at the end of step e), covered by

hardenable material of the respective associated first amount of hardenable material up to the edge.

11. The method of claim 1 including hardening the respective associated first amount of hardenable material to form the respective one of the first elements surrounded laterally by the associated one of the barrier members.